



MOTOROLA

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**MC34064
MC33064**

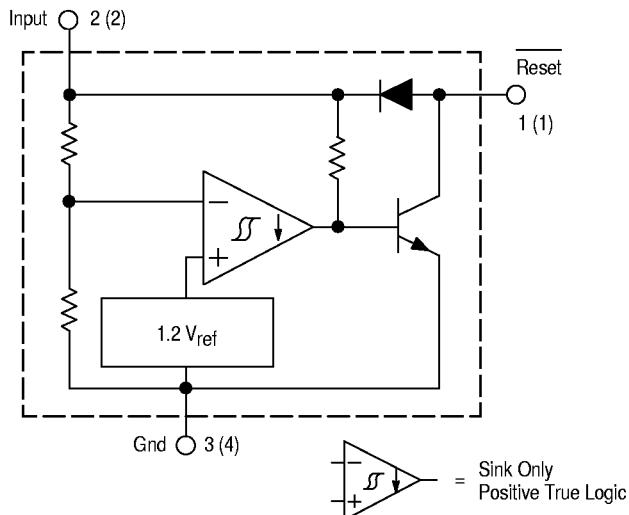
Undervoltage Sensing Circuit

The MC34064 is an undervoltage sensing circuit specifically designed for use as a reset controller in microprocessor-based systems. It offers the designer an economical solution for low voltage detection with a single external resistor. The MC34064 features a trimmed-in-package bandgap reference, and a comparator with precise thresholds and built-in hysteresis to prevent erratic reset operation. The open collector reset output is capable of sinking in excess of 10 mA, and operation is guaranteed down to 1.0 V input with low standby current. These devices are packaged in 3-pin TO-226AA, 8-pin SO-8 and Micro-8 surface mount packages.

Applications include direct monitoring of the 5.0 V MPU/logic power supply used in appliance, automotive, consumer and industrial equipment.

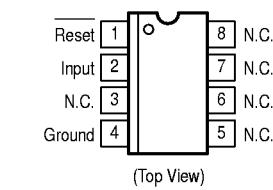
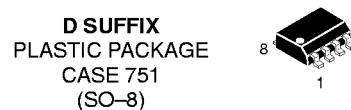
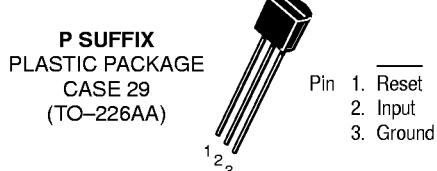
- Trimmed-In-Package Temperature Compensated Reference
- Comparator Threshold of 4.6 V at 25°C
- Precise Comparator Thresholds Guaranteed Over Temperature
- Comparator Hysteresis Prevents Erratic Reset
- Reset Output Capable of Sinking in Excess of 10 mA
- Internal Clamp Diode for Discharging Delay Capacitor
- Guaranteed Reset Operation with 1.0 V Input
- Low Standby Current
- Economical TO-226AA, SO-8 and Micro-8 Surface Mount Packages

Representative Block Diagram



UNDERVOLTAGE SENSING CIRCUIT

SEMICONDUCTOR TECHNICAL DATA



ORDERING INFORMATION

Device	Operating Temperature Range	Package
MC34064D-5	TA = 0° to +70°C	SO-8
MC34064DM-5		Micro-8
MC34064P-5		TO-226AA
MC33064D-5	TA = -40° to +85°C	SO-8
MC33064DM-5		Micro-8
MC33064P-5		TO-226AA

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MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Power Input Supply Voltage	V _{in}	-1.0 to 10	V
Reset Output Voltage	V _O	10	V
Reset Output Sink Current (Note 1)	I _{Sink}	Internally Limited	mA
Clamp Diode Forward Current, Pin 1 to 2 (Note 1)	I _F	100	mA
Power Dissipation and Thermal Characteristics P Suffix, Plastic Package Maximum Power Dissipation @ T _A = 25°C Thermal Resistance, Junction-to-Air	P _D R _{θJA}	625 200	mW °C/W
D Suffix, Plastic Package Maximum Power Dissipation @ T _A = 25°C Thermal Resistance, Junction-to-Air	P _D R _{θJA}	625 200	mW °C/W
DM Suffix, Plastic Package Maximum Power Dissipation @ T _A = 25°C Thermal Resistance, Junction-to-Air	P _D R _{θJA}	520 240	mW °C/W
Operating Junction Temperature	T _J	+150	°C
Operating Ambient Temperature MC34064 MC33064	T _A	0 to +70 -40 to +85	°C
Storage Temperature Range	T _{stg}	-65 to +150	°C

NOTE: ESD data available upon request.

ELECTRICAL CHARACTERISTICS (For typical values T_A = 25°C, for min/max values T_A is the operating ambient temperature range that applies [Notes 2 and 3] unless otherwise noted.)

Characteristics	Symbol	Min	Typ	Max	Unit
COMPARATOR					
Threshold Voltage High State Output (V _{in} Increasing) Low State Output (V _{in} Decreasing) Hysteresis	V _{IH} V _{IL} V _H	4.5 4.5 0.01	4.61 4.59 0.02	4.7 4.7 0.05	V
Output Sink Saturation (V _{in} = 4.0 V, I _{Sink} = 8.0 mA) (V _{in} = 4.0 V, I _{Sink} = 2.0 mA) (V _{in} = 1.0 V, I _{Sink} = 0.1 mA)	V _{OL}	— — —	0.46 0.15 —	1.0 0.4 0.1	V
Output Sink Current (V _{in} , Reset = 4.0 V)	I _{Sink}	10	27	60	mA
Output Off-State Leakage (V _{in} , Reset = 5.0 V)	I _{OH}	—	0.02	0.5	μA
Clamp Diode Forward Voltage, Pin 1 to 2 (I _F = 10 mA)	V _F	0.6	0.9	1.2	V

TOTAL DEVICE

Operating Input Voltage Range	V _{in}	1.0 to 6.5	—	—	V
Quiescent Input Current (V _{in} = 5.0 V)	I _{in}	—	390	500	μA

NOTES: 1. Maximum package power dissipation limits must be observed.

2. Low duty cycle pulse techniques are used during test to maintain junction temperature as close to ambient as possible.

3. T_{low} = 0°C for MC34064
—40°C for MC33064 T_{high} = +70°C for MC34064
 +85°C for MC33064

Figure 1. Reset Output Voltage versus Input Voltage

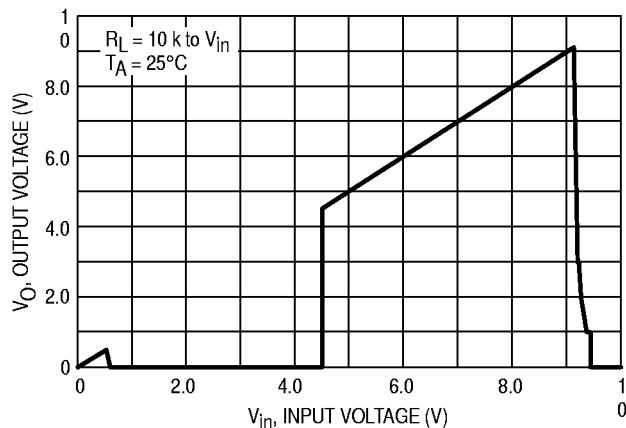


Figure 2. Reset Output Voltage versus Input Voltage

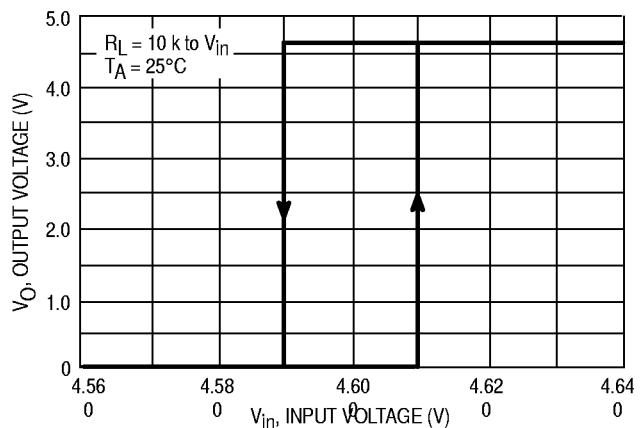


Figure 3. Comparator Threshold Voltage versus Temperature

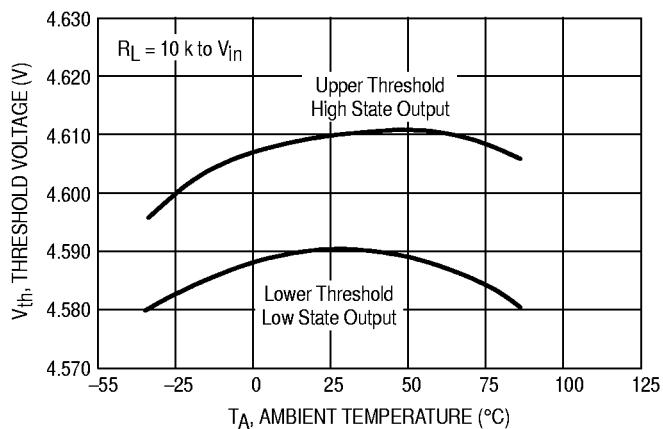


Figure 4. Input Current versus Input Voltage

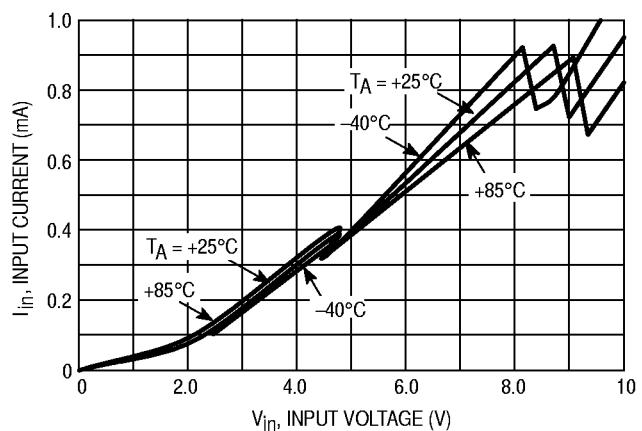


Figure 5. Reset Output Saturation versus Sink Current

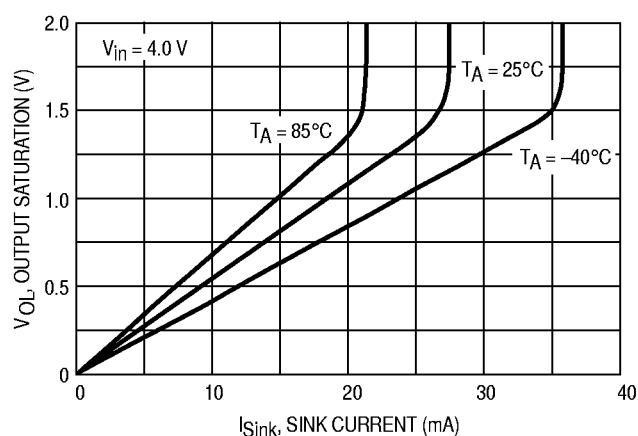
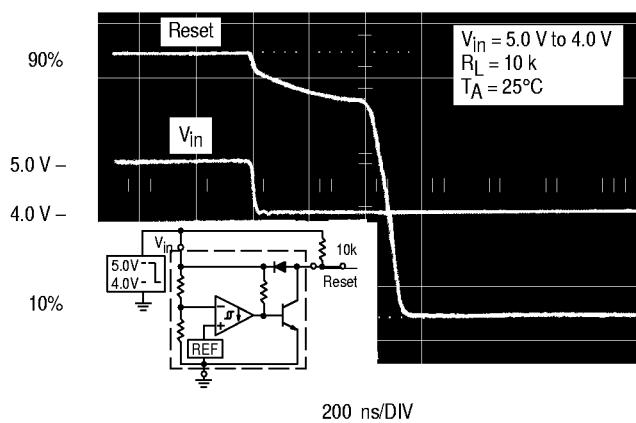


Figure 6. Reset Delay Time



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Figure 7. Clamp Diode Forward Current versus Voltage

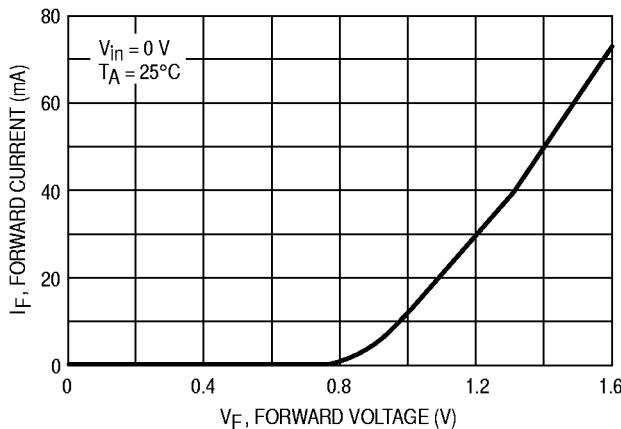


Figure 8. Low Voltage Microprocessor Reset

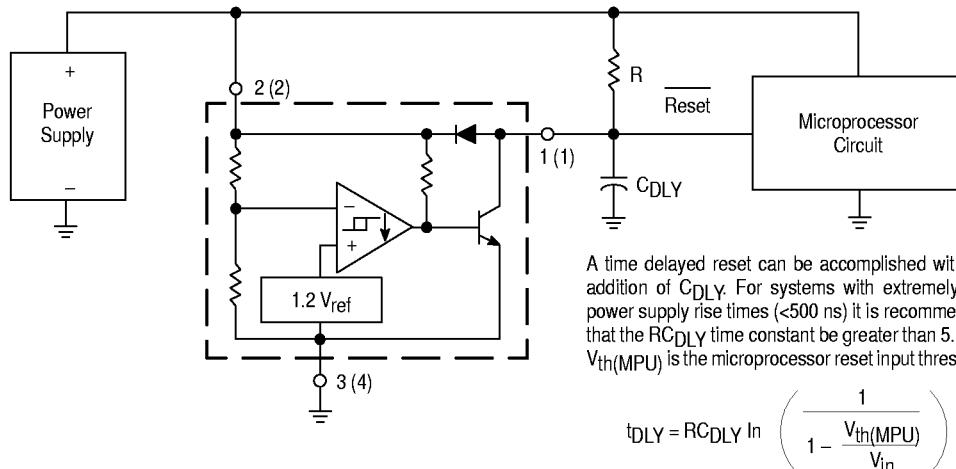
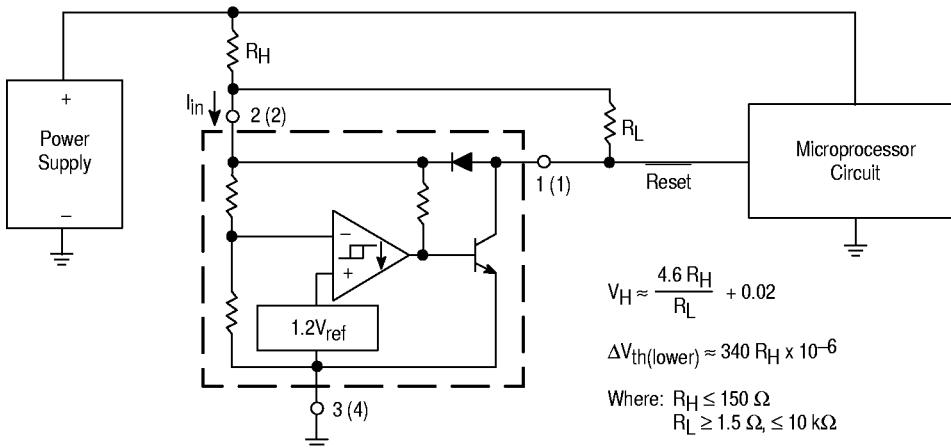


Figure 9. Low Voltage Microprocessor Reset with Additional Hysteresis



Comparator hysteresis can be increased with the addition of resistor R_H . The hysteresis equation has been simplified and does not account for the change of input current I_{in} as V_{CC} crosses the comparator threshold (Figure 4). An increase of the lower threshold $\Delta V_{th(lower)}$ will be observed due to I_{in} which is typically 340 μA at 4.59 V. The equations are accurate to $\pm 10\%$ with R_H less than 150 Ω and R_L between 1.5 $k\Omega$ and 10 $k\Omega$.

Test Data			
V_H (mV)	ΔV_{th} (mV)	R_H (Ω)	R_L ($k\Omega$)
20	0	0	0
51	3.4	10	1.5
40	6.8	20	4.7
81	6.8	20	1.5
71	10	30	2.7
112	10	30	1.5
100	16	47	2.7
164	16	47	1.5
190	34	100	2.7
327	34	100	1.5
276	51	150	2.7
480	51	150	1.5

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Figure 10. Voltage Monitor

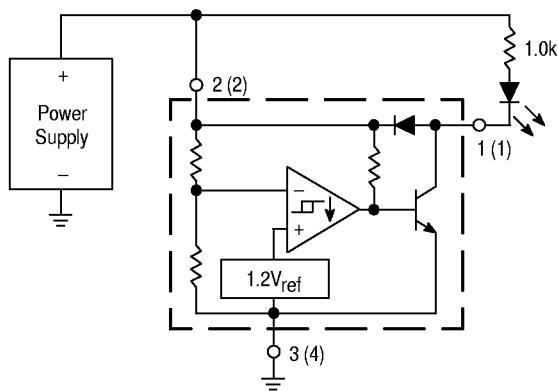


Figure 11. Solar Powered Battery Charger

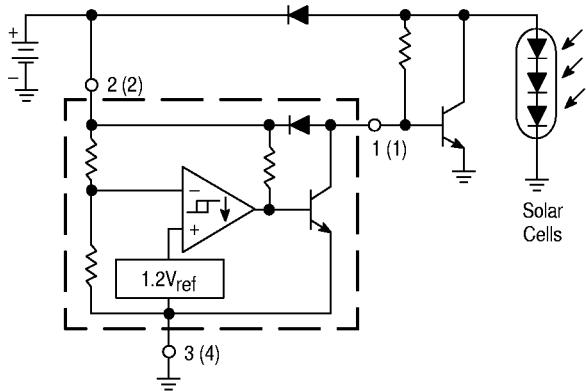
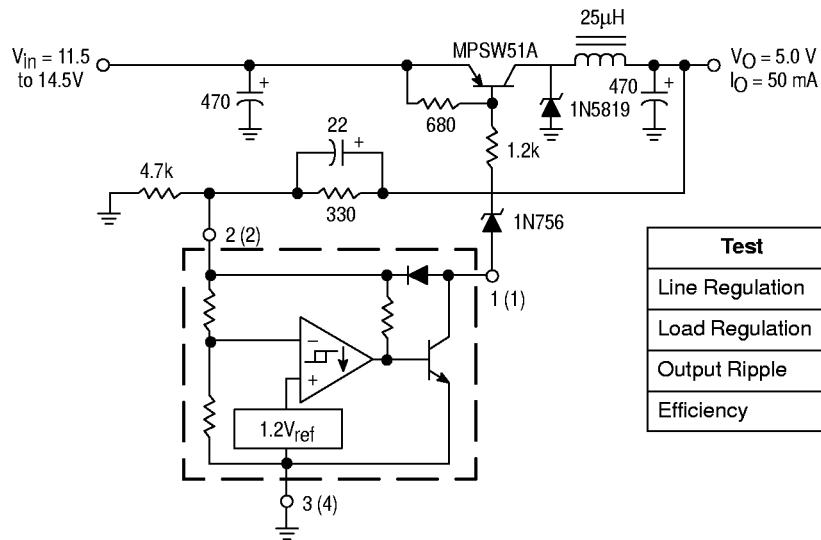
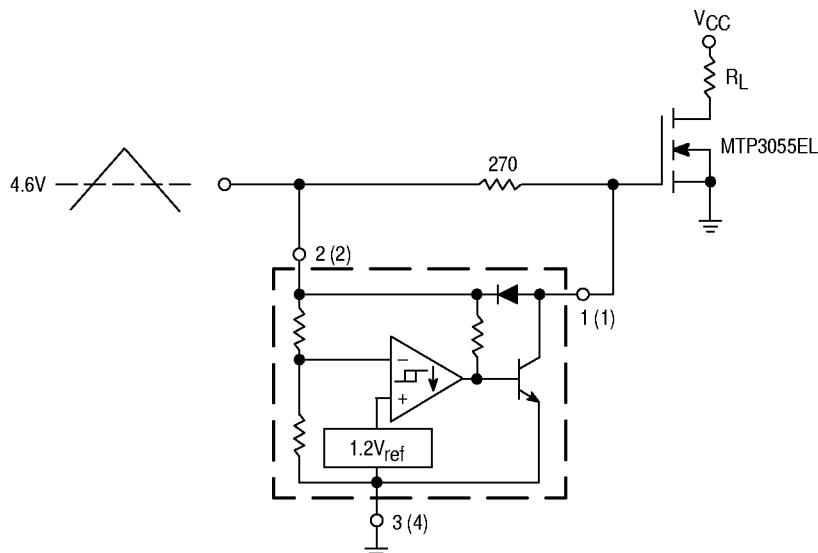


Figure 12. Low Power Switching Regulator



Test	Conditions	Results
Line Regulation	$V_{in} = 11.5 \text{ V to } 14.5 \text{ V}$, $I_O = 50 \text{ mA}$	35 mV
Load Regulation	$V_{in} = 12.6 \text{ V}$, $I_O = 0 \text{ mA to } 50 \text{ mA}$	12 mV
Output Ripple	$V_{in} = 12.6 \text{ V}$, $I_O = 50 \text{ mA}$	60 mVpp
Efficiency	$V_{in} = 12.6 \text{ V}$, $I_O = 50 \text{ mA}$	77%

Figure 13. MOSFET Low Voltage Gate Drive Protection

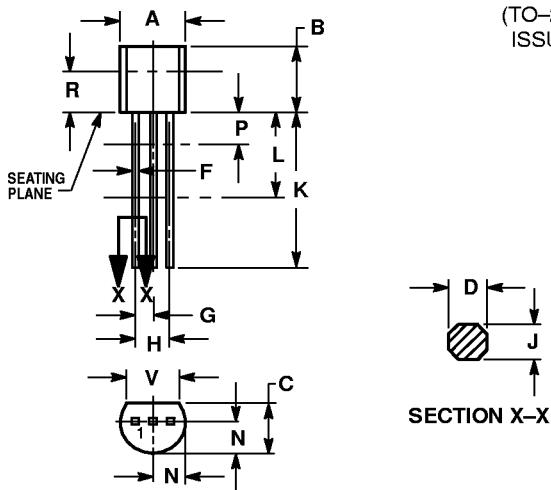


Overheating of the logic level power MOSFET due to insufficient gate voltage can be prevented with the above circuit. When the input signal is below the 4.6 V threshold of the MC34064, its output grounds the gate of the L₂ MOSFET.

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OUTLINE DIMENSIONS

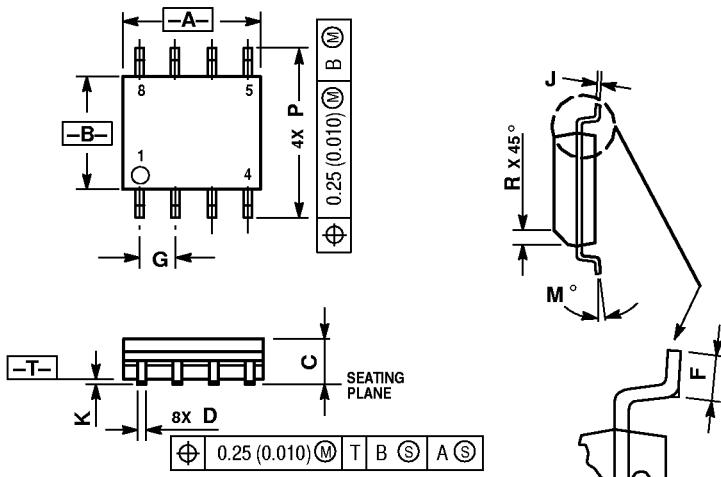
P SUFFIX
PLASTIC PACKAGE
CASE 29-04
(TO-226AA)
ISSUE AD



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
 4. DIMENSION F APPLIES BETWEEN P AND L.
DIMENSION D AND J APPLY BETWEEN L AND K MINIMUM. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.022	0.41	0.55
F	0.016	0.019	0.41	0.48
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	—	12.70	—
L	0.250	—	6.35	—
N	0.080	0.105	2.04	2.66
P	—	0.100	—	2.54
R	0.115	—	2.93	—
V	0.135	—	3.43	—

D SUFFIX
PLASTIC PACKAGE
CASE 751-05
(SO-8)
ISSUE P



- NOTES:
1. DIMENSIONS A AND B ARE DATUMS AND T IS A DATUM SURFACE.
 2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 3. DIMENSIONS ARE IN MILLIMETER.
 4. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
 6. DIMENSION D DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS	
	MIN	MAX
A	4.80	5.00
B	3.80	4.00
C	1.35	1.75
D	0.35	0.49
F	0.40	1.25
G	1.27 BSC	
J	0.18	0.25
K	0.10	0.25
M	0 °	7 °
P	5.80	6.20
R	0.25	0.50

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OUTLINE DIMENSIONS

